

Advanced Semiconductor Packaging in Automotive Electronics

29/09/2026 The decisive factor for automotive compute performance and centralization

Advanced semiconductor packaging is no longer merely a backend manufacturing step. As advanced driver assistance systems and autonomous driving functions become more demanding, bandwidth, thermal management, and system integration are emerging as critical performance drivers. Advanced packaging is therefore becoming a key enabler of compute performance, energy efficiency, and software-defined vehicle architectures.

Porsche Consulting's strategy paper explores why the future of automotive electronics will be determined by more than chip design alone. It examines the technological, economic, and strategic implications of advanced packaging technologies for OEMs, Tier 1 suppliers, and semiconductor players. The paper focuses on rising compute requirements, emerging chiplet architectures, and the actions companies must take to secure performance, resilience, and value creation in the next

generation of vehicle electronics.

Read the whole strategy paper: Advanced Semiconductor Packaging in Automotive Electronics

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